1. Package summary

Terminal position code B (bottom)

Package type descriptive code WLCSP

Package type industry code WLCSP4

Package body material type X (other)

Package style descriptive code

Mounting method type S (surface mount)

UC (uncased chip)

Issue date12-4-2017Manufacturer package codeWLCSP4

Table 1. Package summary

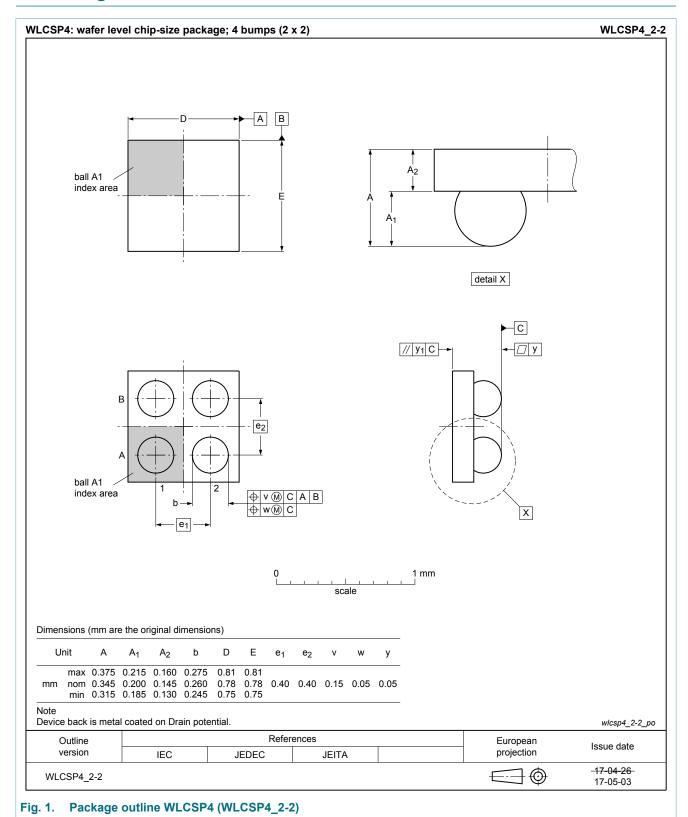
| Symbol | Parameter | Min | Тур | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-------|-------|------|
| D | package length | 0.75 | - | 0.78 | 0.81 | mm |
| E | package width | 0.75 | - | 0.78 | 0.81 | mm |
| Α | seated height | 0.315 | - | 0.345 | 0.375 | mm |
| A ₂ | package height | 0.13 | - | 0.145 | 0.16 | mm |
| е | nominal pitch | - | - | 0.4 | - | mm |
| n ₂ | actual quantity of termination | - | - | 4 | - | |



Nexperia WLCSP4_2-2

wafer level chip-size package; 4 bumps (2 x 2)

2. Package outline

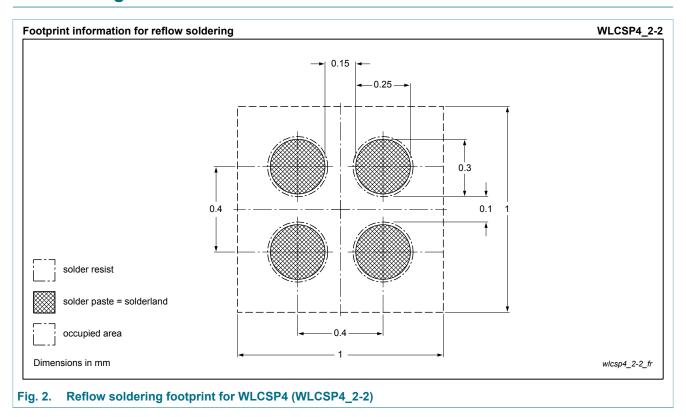


WLCSP4_2-2

Nexperia WLCSP4_2-2

wafer level chip-size package; 4 bumps (2 x 2)

3. Soldering



Nexperia WLCSP4 2-2

wafer level chip-size package; 4 bumps (2 x 2)

4. Legal information

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Nexperia WLCSP4_2-2

wafer level chip-size package; 4 bumps (2 x 2)

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For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 22 June 2017

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